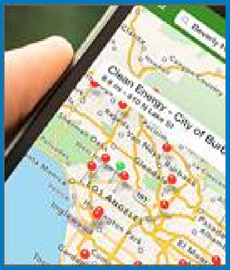
NREL
NATIONAL RENEWABLE ENERGY LABORATORY

Power Electronics Thermal Management R&D



Kevin Bennion
National Renewable Energy Laboratory (NREL)
2015 Annual Merit Review
June 10, 2015

Project ID # EDT069

NREL is a national laboratory of the U.S. Department of Energy, Office of Energy Efficiency and Renewable Energy, operated by the Alliance for Sustainable Energy, LLC.

Overview

Timeline

- **Project Start Date:** FY15
- **Project End Date:** FY17
- **Percent Complete:** 15%

Barriers

- Cost
- Weight
- Performance and Lifetime

Budget

- **Total Project Funding: $625K**
  - DOE Share: $625K
- **Funding for FY15: $625K**

Partners

- Oak Ridge National Laboratory (ORNL) – Power Electronics Lead
- John Deere Electronic Solutions
- Arkansas Power Electronics International (APEI)
- PowerAmerica

Relevance

Objective: Identify and create strategies along thermal and electrical path for better thermal management and reliability through cooling approaches and material selection to enable high-temperature Si and wide-bandgap (WBG) (SiC) devices in power assemblies.

WBG devices (SiC, GaN) promise to increase efficiency, but will be driven as hard as they will go. This still creates challenges for thermal management (and reliability).

Si	Less efficient = More heat Lower junction temperature
WBG	More efficient = Less heat Higher junction temperature Area can be >75% less → increased heat fluxes

Relevance

Why thermal management?

- Limit failure, increase reliability
- Margin on component thermal constraints
- Manage heat flow and dissipate or remove heat
- Power density increase

What feature(s) could be engineered to get more out of the same components?

What are the tradeoffs and where can dividends in improved technology pay off?

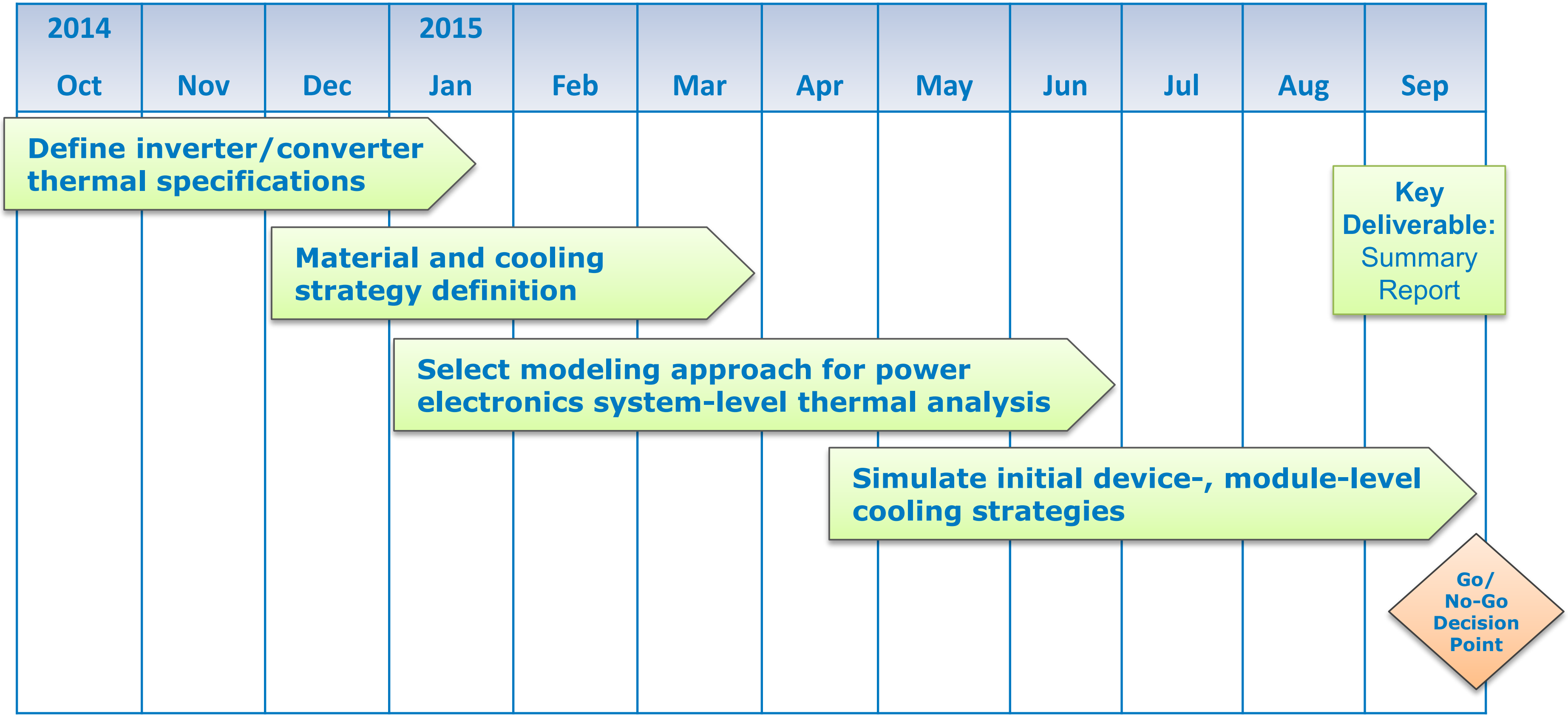
Cost tradeoffs to get higher performance, lower volume and weight:

- Material costs
- Production costs (capacity costs, throughput/yield)
- Process cost
- Reliability (replacement cost, de-rating, safety, reputation).

Milestones

Month/ Year	Milestone or Go/No-Go Decision	Description	Status
12/14	Milestone	Define and list the thermal specifications and constraints for WBG-based inverter.	Met
03/15	Milestone	Define and list potential material and geometry variations for thermal management analysis.	Met
06/15	Milestone	Select the modeling approach for power electronic system-level analysis and begin running models with thermal and material variations.	In Progress
09/15	Milestone	Prepare summary report on comparison of current and proposed cooling strategies for WBG-based inverter and converters.	Upcoming
9/15	Go/No-Go	If there are concepts that contribute towards meeting 2022 targets, proceed to advanced analysis, simulation, and benchtop testing of concepts	

Approach/Strategy – Schedule



Go/No-Go Decision Point: If there are concepts that contribute towards meeting 2022 targets, proceed to advanced analysis, simulation, and benchtop testing of concepts.

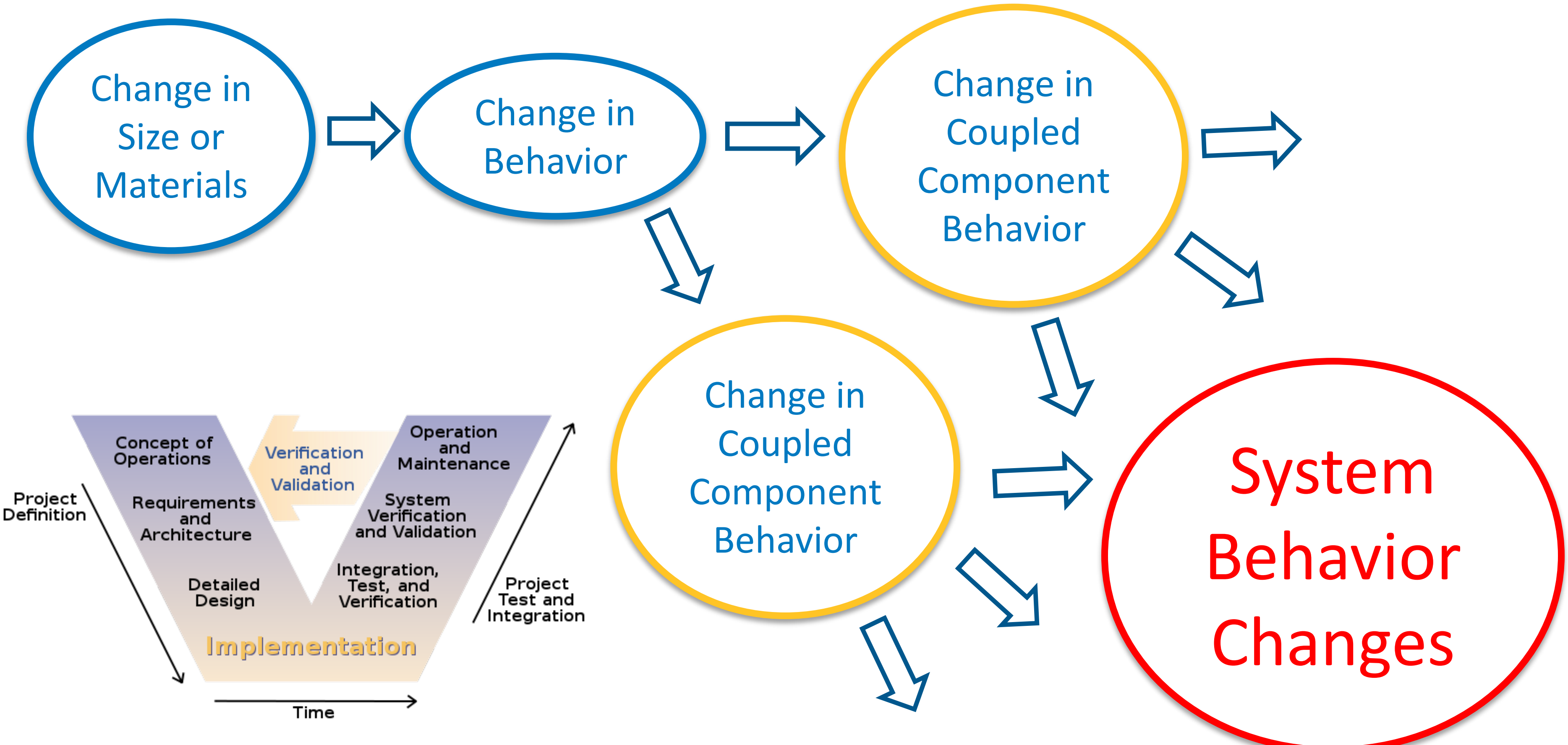
Key Deliverable: Summary report (incorporated into annual report) providing comparison of packaging concepts and cooling strategy thermal performance.

Approach/Strategy

1) Look at existing technology (baseline benchmarking).
2) Examine system with high-temperature devices.
3) Define where there are thermal bottlenecks.
4) Examine what can be enhanced (materials, cooling strategies) considering costs and manufacturing process.
5) Create alternatives to reduce or mitigate impact of thermal bottlenecks.

Approach/Strategy

Component coupling can affect system behavior



Federal Highway Administration, 2005, “Clarus, Concept of Operations,” Publication No. FHWA-JPO-05-072.

Approach/Strategy

2012 Nissan Leaf Inverter

Higher power levels produce thermal pathways into undesirable locations.

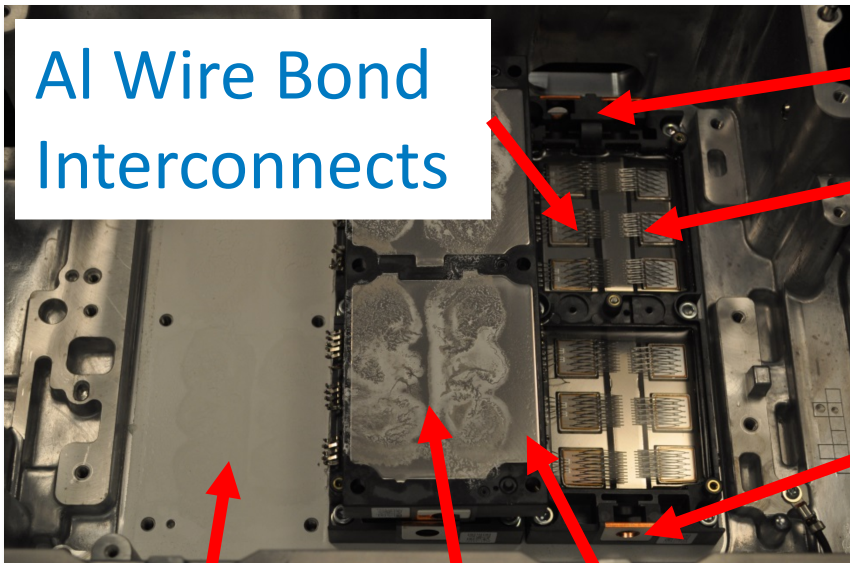


Photo credit: Scot Waye, NREL

DC Interconnect

Device (IGBT/Diode)

- Heat generation
- Passive stack (substrate, TIM) thermal resistance

AC Interconnect

Electric Isolation Film

Thermal Interface Material (TIM)

Electrically Active Plate

Approach/Strategy

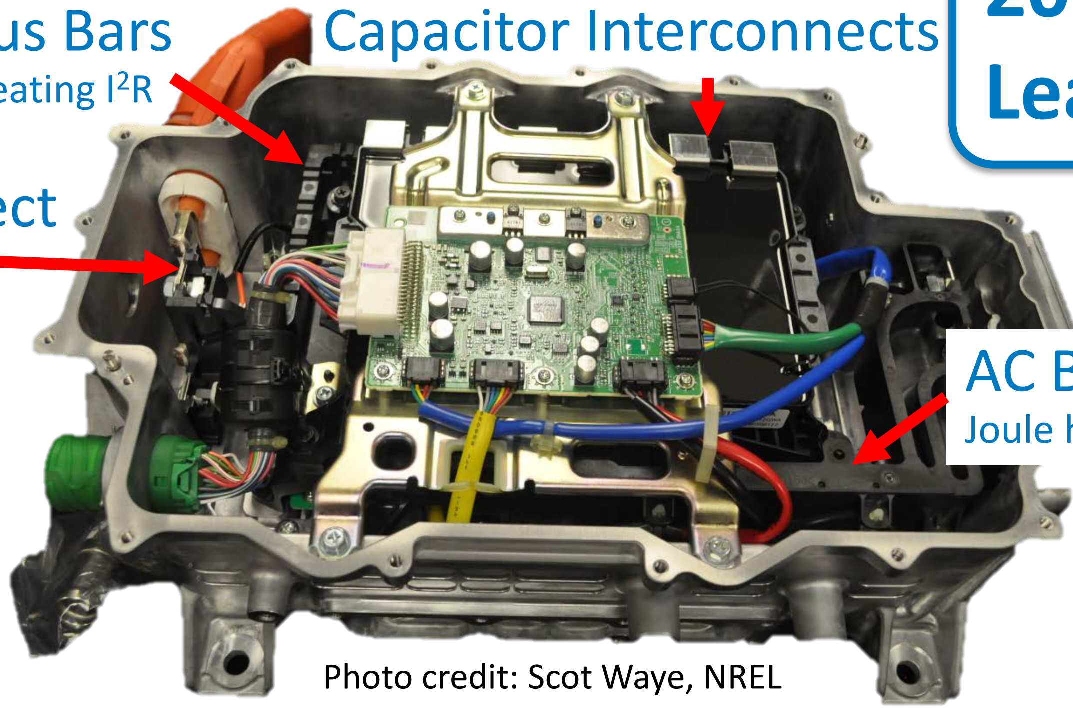


Photo credit: Scot Waye, NREL

Resistance Heat Generation

- Measure thermal, electrical resistances
- Calculate Joule heating.

Approach/Strategy

Power Assembly Improvements

- Increased Integration
- Improved Cooling

[3]

photo credit: Gilbert Moreno, NREL

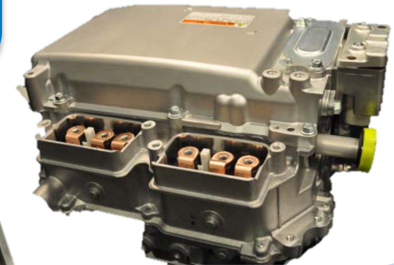
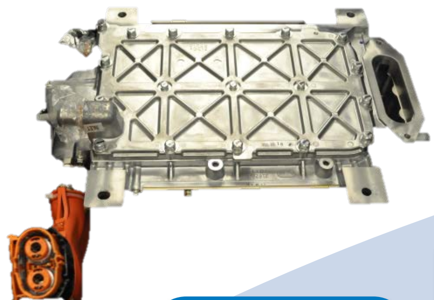


photo credit: Scot Waye, NREL



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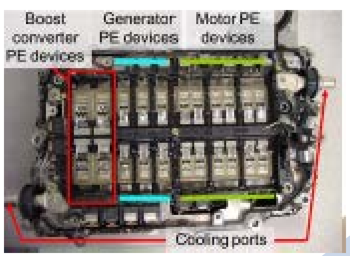
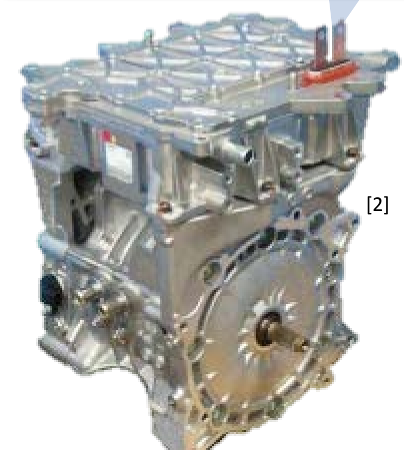


Motor + Inverter Integration

Double-sided Cooling

Direct Cooling

Inverter (Motor + Generator) + Boost Integration



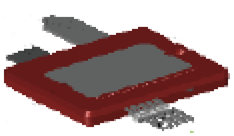
[2]

[1] Yole Développement, 2015, "EV-HEV Market and Technology Trends," APEC 2015, Charlotte, NC.
[2] Shimizu et al., 2013, "Development of an Integrated Electrified Powertrain for a Newly Developed Electric Vehicle," SAE International, Detroit, MI.
[3] Grewe et al., 2015, "Generation Two VOLTEC Drive System," SAE EV/HEV Symposium, Los Angeles, CA.

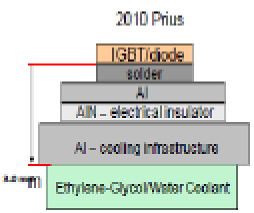
Approach/Strategy

<u>Power Module Packaging Improvements</u>

- Increased Integration
- Improved Cooling
- Capable for High Frequencies

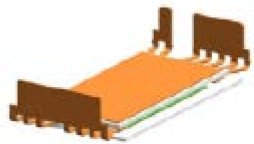


<u>Denso/Lexus 600h 2008</u>
Single IGBT/Diode package
Flip-chip soldering
Double-sided cooling
Costly

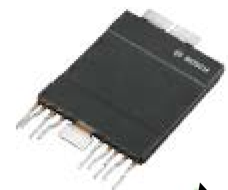


<u>Toyota Prius 2010</u>
Standard packaging
Ribbon bonding
Direct cooling

<u>Honda 2010</u>
Epoxy packaging
Cu lead bonding
Direct cooling



<u>Delphi 2010</u>
Single IGBT/diode package
Flip-chip soldering
Direct cooling



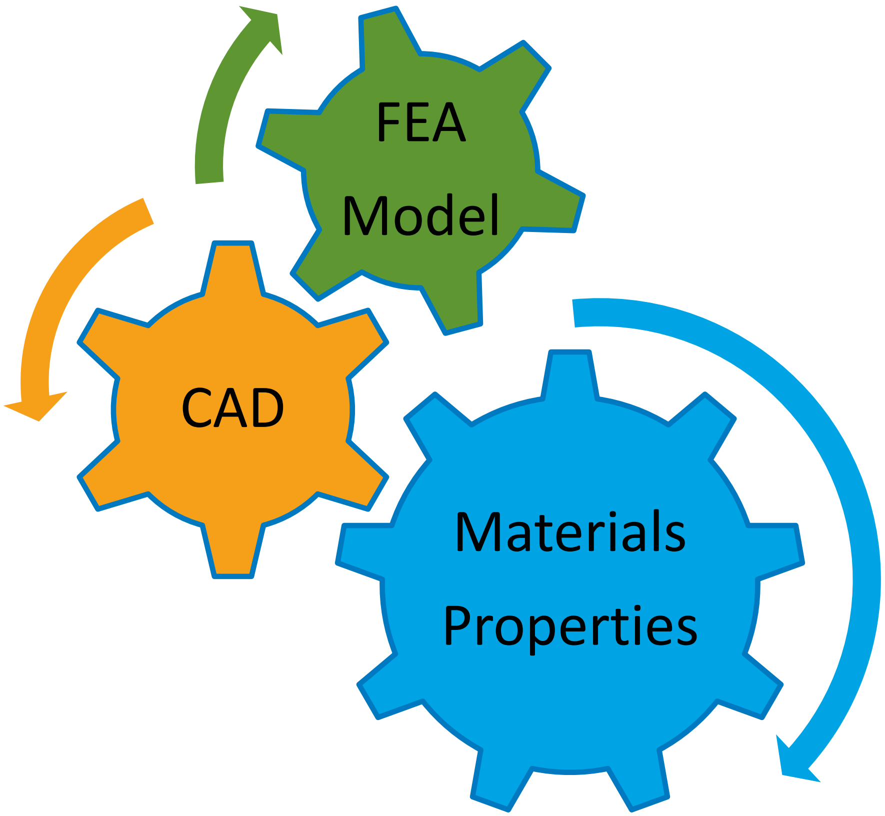
<u>Bosch 2013</u>
Molded package
Die on leadframe
Copper layer for thermal spreading
Direct cooling

<u>Mitsubishi 2014</u>
Six-pack IGBT/Diode package
Cooling fin
Copper layer for thermal spreading
Direct cooling

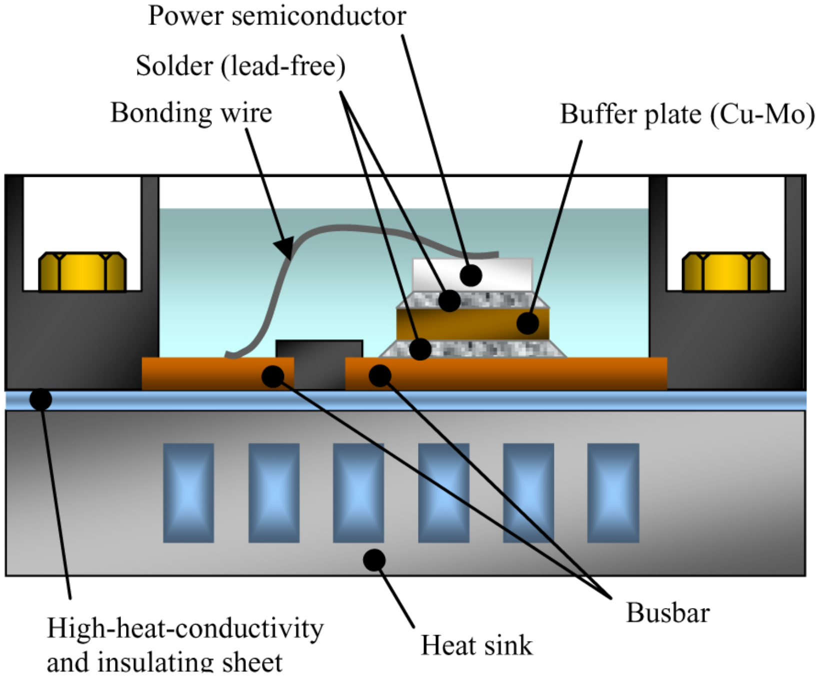
Photo credits: Yole Développement, 2015, “EV-HEV Market and Technology Trends,” APEC 2015, Charlotte, NC.

Technical Accomplishments and Progress

- Literature Search
  - Inverter topologies
  - Previously benchmarked PE
  - Cooling strategies
  - Material properties
- Platform Selection
  - 2012 Nissan Leaf ("standard")
  - Open to examine others
  - Disassembly of inverter
- Modeling Method Selected
  - CAD model
  - Thermal FEA for steady-state conduction/convection → thermal maps and bottlenecks
  - CFD if necessary to examine other cooling strategies



Technical Accomplishments and Progress



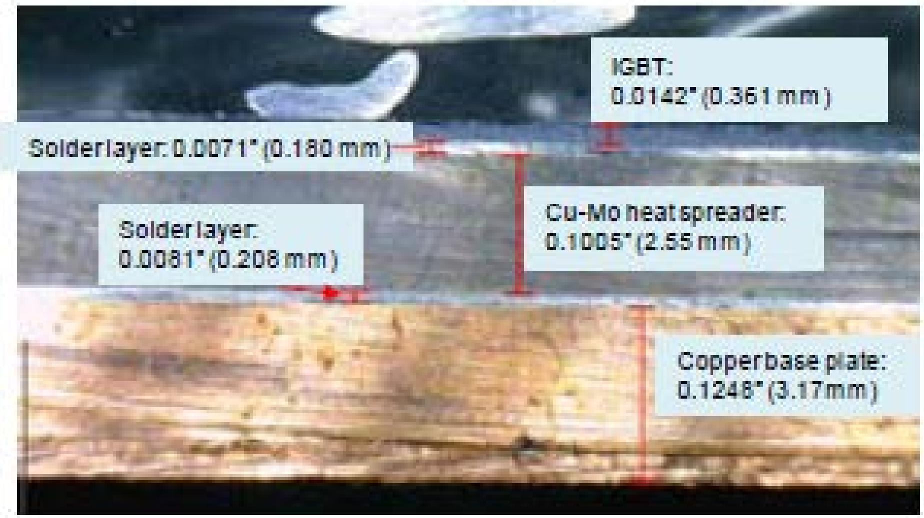
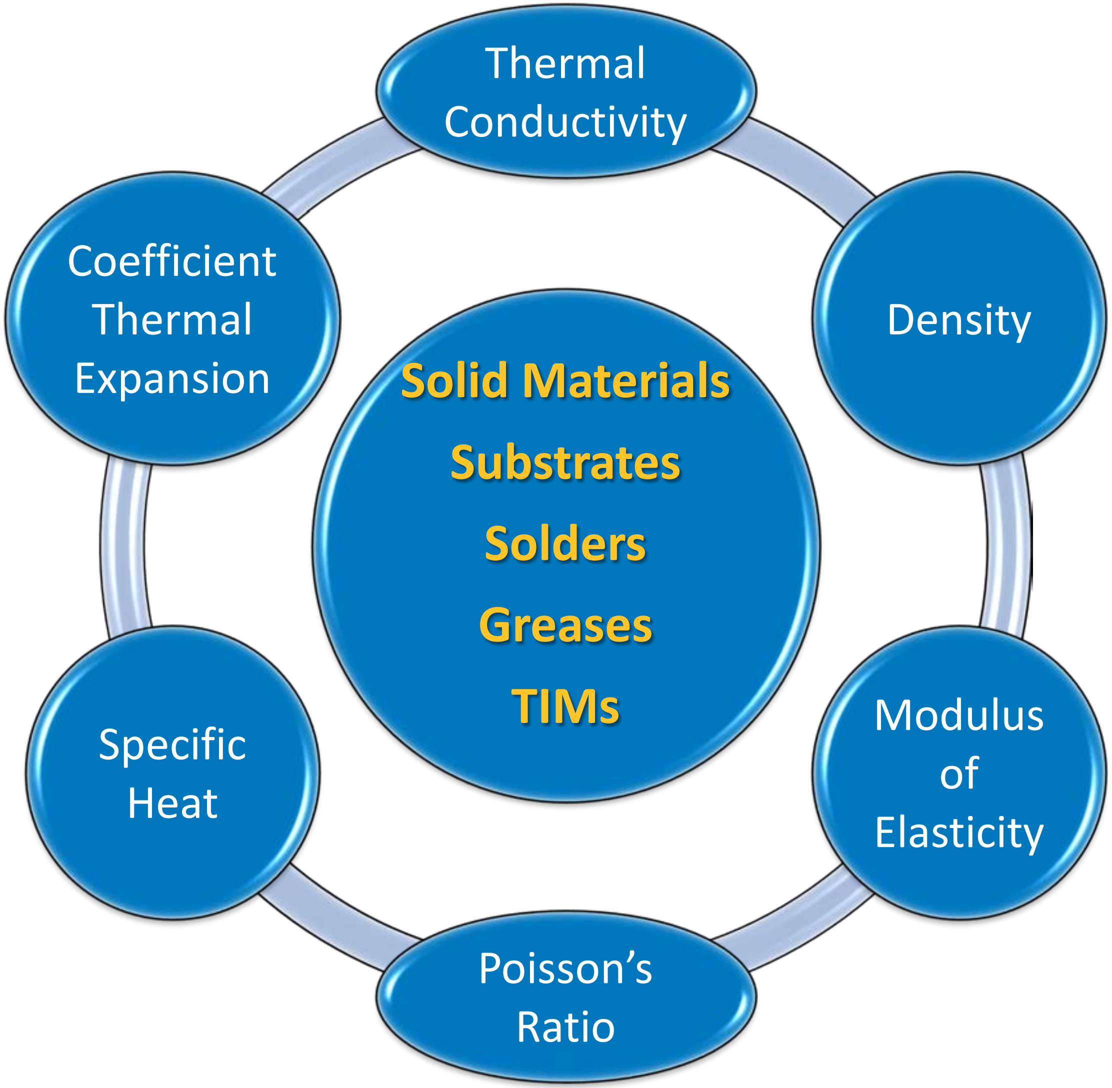


Photo credit: Tim Burress, ORNL

- 2012 Nissan Leaf benchmarking (ORNL) defined thermal stack-up (also seen at NREL)
- NREL conducting thermal benchmarking

Sato et al., 2011, "Development of High Response Motor and Inverter System for the Nissan LEAF Electric Vehicle," SAE International, Detroit, MI.

Technical Accomplishments and Progress



Established database of material properties to consider for package assembly and power assembly

Technical Accomplishments and Progress

Developed appropriate database of solder/TIMs

Anand Properties	Material Property
A (sec-1)	Pre-exponential factor
Q/R (J/mol)	Q = Activation energy R = Universal gas constant
Ŝ (MPa)	Coefficient for deformation resistance saturation value
h_0 (MPa)	Hardening/softening constant
ξ	Stress multiplier
m	Strain rate sensitivity of stress
n	Strain rate sensitivity of saturation (deformation resistance)
a	Strain rate sensitivity of hardening or softening
s_0 (MPa)	Initial value of deformation resistance

- Lead Solders
- Lead-free Solders
- Sintered Silver

Technical Accomplishments and Progress

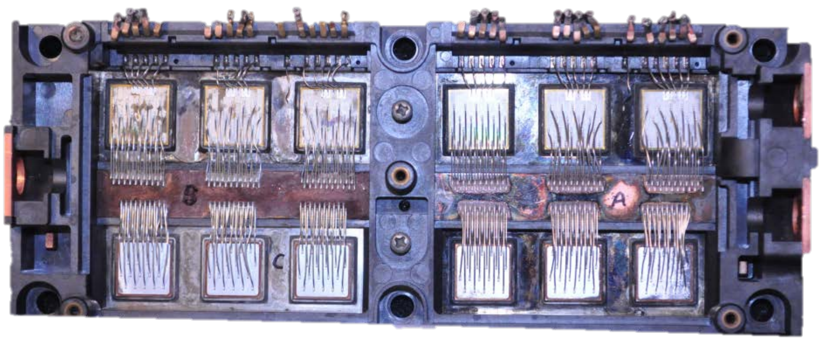
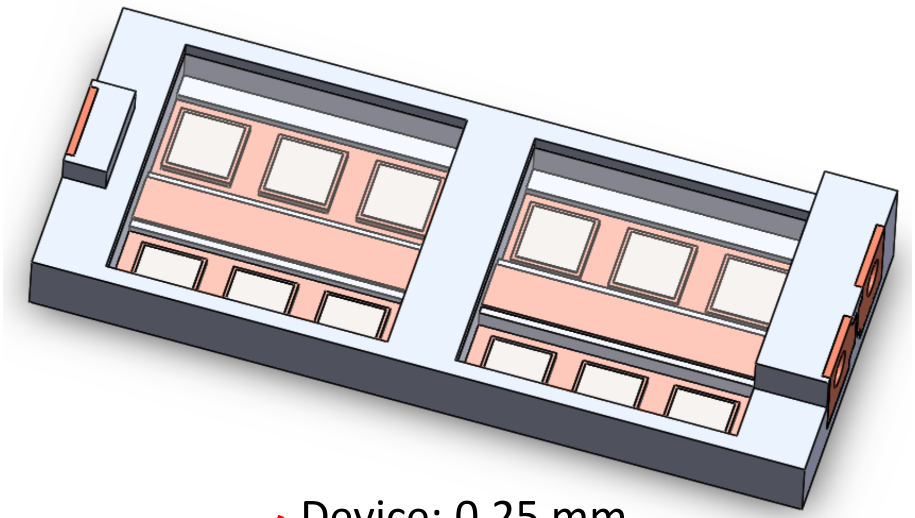
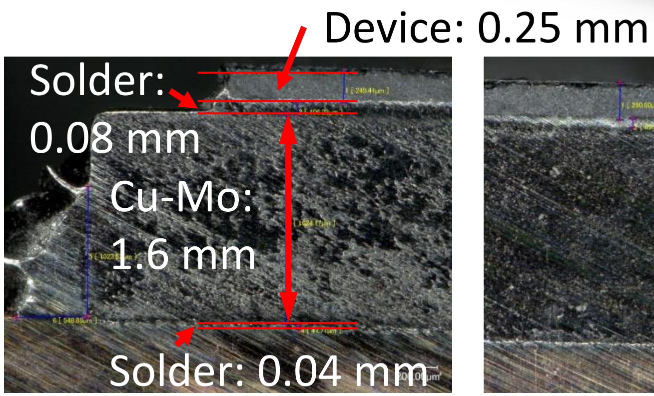


Photo credits: Charlie King, NREL

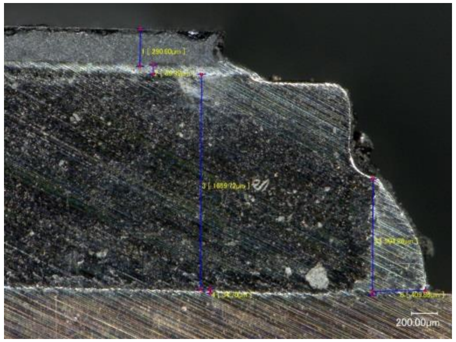


Bottom - electrically active

(color due to soaking module to dissolve potting material)



Diode



IGBT

CAD model of module drawn and being imported into thermal FEA model setup

Responses to Previous Year Reviewers' Comments

New project for FY15; not reviewed last year.

Collaboration and Coordination with Other Institutions

Organization	Role
APEI	Industry comments on packaging and thermal management challenges
John Deere Electronic Solutions	Industry technical challenge information
Oak Ridge National Laboratory	PE R&D (inverter/converter/charger projects) – NREL will provide thermal management support
PowerAmerica (WBG Institute)	Collaborations and interactions with Institute members on thermal management challenges

Actively pursuing additional industry partners (OEM, Tier 1/2 suppliers) interested in providing technical support, suggestions, or collaborations.

Remaining Challenges and Barriers

- **Understanding tradeoffs of:**
  - Thermal performance (low resistance)
  - Reliability of materials, cooling strategies
  - Cost of implementing into system
  - Integration effects on other components/systems

Proposed Future Work

FY15

- Thermal Model for Module
  - Examine various TIMs and thicknesses.
  - Examine cooling strategies (single-phase liquid, air, two-phase, enhanced surfaces, baseplate removal).
  - Examine different substrate/baseplate/TIM combinations.

FY16

- Expand Thermal Analysis
  - Examine interconnections (bus bars) cooling.
  - Monitor other component thermal constraints (capacitors).
  - Generate assembly topologies to limit thermal exposure.
  - Consider transient behavior.

Summary

- New project aims to identify and create strategies for better thermal management for WBG and high-temperature device use in vehicular power electronics and assemblies.
- Approach is to travel along thermal and electrical path to identify and generate solutions to thermal bottlenecks.
- Modeling will be used – experiments may validate models or concepts.
- What features can be engineered or the process modified to get more out of the system for relatively incremental cost penalties?
- What change in assembly can protect critical components from excessive thermal exposure?
- Modeling efforts have begun as information gathering is completed.

Acknowledgments:

Susan Rogers and Steven Boyd,
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Team Members:

Kevin Bennion (NREL)
Charlie King (NREL)
Gilbert Moreno (NREL)

For more information, contact:

Principal Investigator
Scot Waye
Scot.Waye@nrel.gov
Phone: (303)-275-4447

EDT Task Leader:

Sreekant Narumanchi
Sreekant.Narumanchi@nrel.gov
Phone: (303)-275-4062